

L Number	Hits	Search Text	DB	Time stamp
-	104	(rapid adj thermal or rta or rtp or heat adj treat\$4 or anneal\$4 or ptp) same (silicon or si) near2 (wafer) same temperature same (seconds or minutes or sec or min or hours or hour or hr or hrs) and 117/\$4.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/21 10:15
-	91	(rapid adj thermal or rta or rtp or heat adj treat\$4 or anneal\$4 or ptp) same (silicon or si) near2 (wafer) same temperature same (seconds or minutes or sec or min) and 117/\$4.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 17:00
-	128	(rapid adj thermal or rta or rtp or heat adj treat\$4 or anneal\$4 or ptp) same (silicon or si) near2 (wafer) same temperature same (seconds or minutes or sec or min) and 117/\$4.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 17:08
-	39	(rapid adj thermal or rta or rtp or heat adj treat\$4 or anneal\$4 or ptp) same (silicon or si) near2 (wafer) same temperature same (seconds or minutes or sec or min) same (hydrogen or h2 or "h.sub.2") and 117/\$4.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/14 17:10